

AMENDMENTS TO THE CLAIMS:

Please cancel without prejudice claims 1-15 and amend claims 17-19 and 21 as follows.

This listing of claims will replace all prior versions, and listings, of claims in the application:

1 – 15. (Cancelled)

16. (Original) A method of producing an ultrasonic transducer comprising applying a sacrificial material to a substrate, applying a polymer coating over at least part of the sacrificial material and the substrate, and removing at least part of the sacrificial material to leave a portion of the polymer coating defining a movable member wherein the member defines a part of a single cavity, and in which the polymer is applied in a mobile state.

17. (Currently Amended) A method according to Claim 16 in which the polymer coating which defines the movable member is applied over substantially ~~the whole~~all of the sacrificial material and contacts the substrate around the cavity.

18. (Currently Amended) A method according to Claim 16 in which the polymer coating is applied at a thickness so as to produce ~~at the~~ movable member that is of the order of 2 μm thick, or less.

19. (Currently Amended) A method according to claim 16 in which, as the polymer is applied in ~~at the~~ mobile state, the sacrificial material assists in defining a non-flat shape of ~~at the~~ movable ~~polymer membrane~~member, and which further comprises removing the sacrificial material after the shape of the movable ~~polymer~~ member has been established.

20. (Previously Presented) A method according to claim 16 in which the substrate is a semiconductor material.

21. (Currently Amended) A method according to claim 16 comprising applying a top contact pad material onto the top of the ~~membrane~~movable member, and etching the top contact pad material through a mask to define a top contact pad.

22. (Previously Presented) A method according to claim 16 which comprises producing an array of transducers on the same substrate.

23. (Original) A method according to Claim 22 which further comprises ensuring that there are transducers in the array which respond to different frequencies.

24. (Previously Presented) A method according to claim 16 which further comprises providing an integrated semiconductor device having the transducer and having signal processing means provided on the same substrate.